

APPLICATION DATA SHEET

Application Information

Application Type:: Regular
Subject Matter:: Utility
Suggested Classification::
Suggested Group Art Unit::
Title:: A METHOD OF ASSEMBLING A
SEMICONDUCTOR DEVICE PACKAGE
Attorney Docket Number:: INF 4384
Request for Early Publication?:: No
Request for Non-Publication?:: No
Suggested Drawing Figure::
Total Drawing Sheets::
Small Entity?:: No

Applicant Information

Applicant Authority Type:: Inventor
Primary Citizenship Country:: Singapore
Status:: Full Capacity
Given Name:: Charles
Family Name:: Lee
City of Residence:: Singapore
Country of Residence:: Singapore
Street of Mailing Address:: Apt. Blk 110, Bukit Purmei Road
#03-152
City of Mailing Address:: Singapore
Postal Code of Mailing Address:: 090110

Applicant Authority Type:: Inventor
Primary Citizenship Country:: Austria
Status:: Full Capacity
Given Name:: Helmut
Family Name:: Strack
City of Residence:: Munich
Country of Residence:: Germany
Street of Mailing Address:: Speyererstrasse 6,
City of Mailing Address:: Munich
Postal Code of Mailing Address:: D-80804

Correspondence Information

Correspondence Customer Number:: 000321

Representative Information

Representative Customer Number:: 000321

Foreign Priority Information

Country::	Application number::	Filing Date::	Priority Claimed::
PCT	PCT/SG99/00050	05/31/1999	Yes

Assignee Information

Assignee Name:: Infineon Technologies AG